

CLAIM AMENDMENTS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-11 (canceled).

Claim 12 (previously presented). An electronic unit, comprising:

a printed circuit board having a central region populated with electronic components on both sides thereof, and an edge region adjoining said central region;

a housing enclosing said printed circuit board, said housing having a housing floor and a housing cover connected to said housing floor, said housing floor, when viewed in cross-section, having at least one indentation and housing internal lateral sections;

said central region of said printed circuit board being disposed spaced apart from said housing and said edge region being connected to said housing internal lateral sections via a heat-conducting adhesive layer;

said housing cover having an edge formed with an annularly continuous projection engaging into a corresponding groove formed in said housing floor, said projection and said groove together forming a groove-and-projection connection and being glued to one another.

Claim 13 (previously presented). The electronic unit according to claim 12 configured as a control device for a motor vehicle and populated with electronic components for controlling the motor vehicle.

Claim 14 (previously presented). The electronic unit according to claim 12, wherein a common adhesive is used for said glued groove-and-projection connection and for said adhesive layer connecting said printed circuit board and said housing.

Claim 15 (previously presented). The electronic unit according to claim 12, which comprises at least one plug connector integrated in said housing cover for electrically connecting said electronic unit.

Claim 16 (previously presented). The electronic unit according to claim 15, wherein said plug connector includes terminal pins running straight to said printed circuit board and forming direct contact with said printed circuit board.

Claim 17 (previously presented). The electronic unit according to claim 16, wherein said terminal pins contact said circuit board via press-in contacts.

Claim 18 (previously presented). The electronic unit according to claim 12, wherein said edge region is a printed circuit board section running along a large part of an edge of said printed circuit board.

Claim 19 (previously presented). The electronic unit according to claim 18, wherein said edge region is a printed circuit board section running in an annularly continuous manner along said edge of said printed circuit board.

Claim 20 (previously presented). The electronic unit according to claim 12, wherein said edge region has first side at least partly populated with the electronic components, and a second side connected with said heat-conducting adhesive layer.

Claim 21 (currently amended). A method for manufacturing an electronic unit, which comprises the following steps:

a) providing a printed circuit board with at least one first printed circuit board section in a central area thereof, being populated on both sides with electronic components, and having at least one second printed circuit board section arranged at an edge of the printed circuit board and having one side not populated with electronic components;

b) providing a contoured housing floor having raised housing internal sections disposed in correspondence with the at least one second printed circuit board section, and having an annularly continuous groove running around an edge of the housing floor, the annularly continuous groove formed in the edge of the housing floor;

c) depositing heat-conducting adhesive on the raised housing internal sections;

d) pressing on the printed circuit board in order to bond the printed circuit board on the raised housing internal sections;

e) providing a housing cover having a projection configured to mate in annularly continuous circumferential engagement with the groove of the housing floor, pressing the housing cover onto the housing floor with adhesive disposed to create a glued groove-and-projection connection between housing floor and housing cover.

Claim 22 (previously presented). The method according to claim 21, which comprises depositing the adhesive on the base of the circumferential groove prior to the step of pressing the housing cover onto the housing floor.

Claim 23 (previously presented). The method according to claim 21, wherein a common adhesive is used in the steps c) and e).

Claim 24 (new). The method according to claim 21, which further comprises performing steps c) and d) to enable the raised housing internal sections to dissipate heat away from the printed circuit board and to serve as a main support for the printed circuit board.

Claim 25 (new). The electronic unit according to claim 12, wherein said housing internal lateral sections dissipate heat away from said printed circuit board and serve as a main support for said printed circuit board.